## **MA4GP907**



GaAs

Flip Chip PIN Diode

RoHS Compliant

M/A-COM Products

Rev. V6

#### **Features**

- Low Series Resistance
- ♦ Ultra Low Capacitance
- Millimeter Wave Switching & Cutoff Frequency
- 2 Nanosecond Switching Speed
- ◆ Can be Driven by a Buffered TTL
- Silicon Nitride Passivation
- Polyimide Scratch Protection
- RoHS Compliant

## **Description**

M/A-COM's MA4GP907 is Gallium Arsenide (GaAs) flip-chip PIN diode. It is fabricated using an OMCVD epitaxial wafer with a process designed for high device uniformity and extremely low parasitics. The diode exhibits an extremely low RC product, (0.1ps) and 2-3nS switching characteristics. They are fully passivated with silicon nitride and have an added polymer layer for scratch protection. The protective coating prevents damage to the junction and the anode air-bridge during handling and assembly.

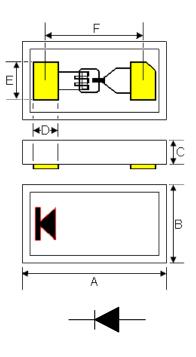
## **Applications**

The ultra low capacitance of the MA4GP907 allows for operation up to millimeter frequencies for RF switches and switched phase shifter applications. The diode is designed for use in pulsed or CW applications, where single digit nS switching speed is required. The low capacitance of the MA4GP907 makes it for use in microwave multi-throw switch assemblies, where the series capacitance of each "off" port adversely loads the input and affects VSWR.

# Absolute Maximum Ratings T<sub>AMB</sub> = +25°C (unless otherwise specified)

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Parameter	Absolute Maximum		
Reverse Voltage	50V		
Operating Temperature	-55°C to +125°C		
Storage Temperature	-55°C to +150°C		
Junction Temperature	+175°C		
Dissipated Power ( RF & DC )	50mW		
C.W. Incident Power	+23 dBm		
Mounting Temperature	+280°C for 10 seconds		

## **Chip Dimensions**



#### Notes:

- 1. Gold Pads 14µM thick.
- 2. Yellow areas indicate ohmic gold mounting pads.

Inches		hes	Millimeters		
DIM	MIN.	MAX.	MIN.	MAX.	
Α	0.026	0.027	0.6604	0.6858	
В	0.0135	0.0145	0.3429	0.3683	
С	0.0065	0.0075	0.1651	0.1905	
D	0.0043	0.0053	0.1092	0.1346	
E	0.0068	0.0073	0.1727	0.1854	
F	0.0182	0.0192	0.4623	0.4877	

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## Electrical Specifications @ T<sub>AMB</sub> = +25°C

Parameter	Symbol	Conditions	Units	Тур.	Max.
Total Capacitance	Ст	-10V,1MHz	pF	0.025	0.030
Total Capacitance <sup>1</sup>	Ст	-10V,10GHz	pF	0.025	
Series Resistance	Rs	+10mA, 1MHz	Ω	5.2	7.0
Series Resistance <sup>2</sup>	Rs	+10mA, 10GHz	Ω	4.2	
Forward Voltage	V <sub>F</sub>	+10mA	V	1.33	1.45
Reverse Voltage Current <sup>3</sup>	I <sub>R</sub>	V <sub>R</sub> = -50V	μΑ		10
Switching Speed <sup>4</sup>	T <sub>RISE</sub> T <sub>FALL</sub>	10GHz	nS	2	

## Notes:

- 1) Capacitance is determined by measuring the isolation of a single series diode in a  $50\Omega$  transmission line at 10GHz.
- 2) Series resistance is determined by measuring the insertion loss of a single series diode in a  $50\Omega$  transmission line at 10GHz.
- 3) The max rated  $V_R($  Reverse Voltage ) is sourced and the resultant reverse leakage current, Ir, is measured to be  ${<}10\mu A$
- 4) Switching speed is measured between 10% and 90% or 90% to 10% RF voltage for a single series mounted diode. Driver delay is not included.

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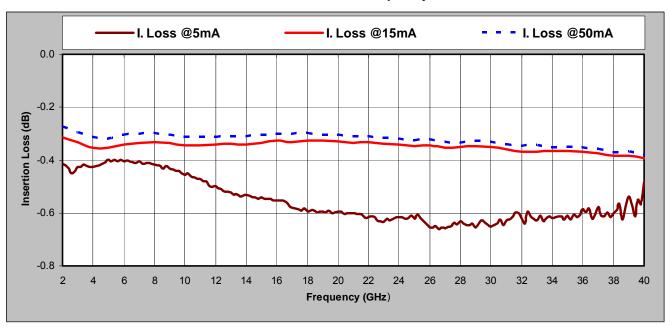
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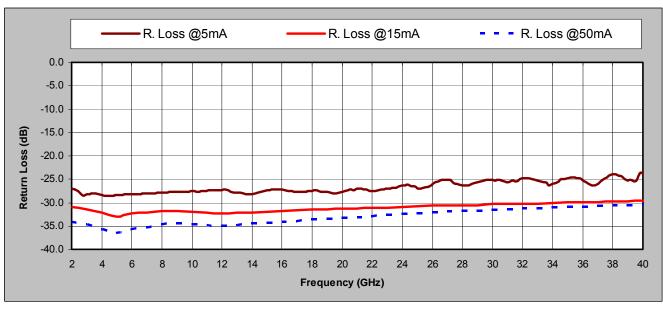
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## Typical RF Performance @ T<sub>AMB</sub> = +25°C

## Insertion Loss vs. Frequency



## **Return Loss vs. Frequency**



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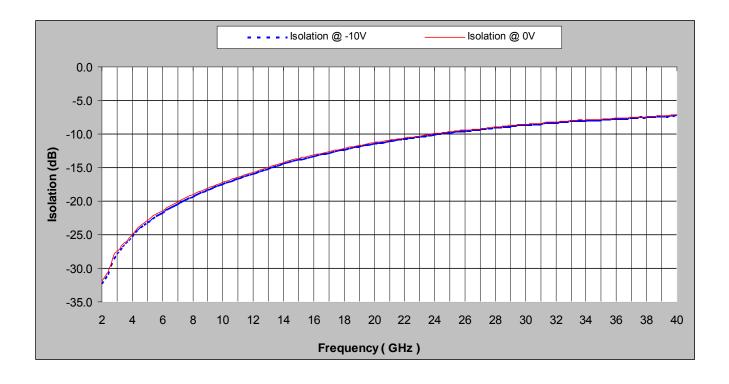
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## Typical RF Performance @ $T_{AMB} = +25$ °C

## Isolation vs. Frequency



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## **Device Installation Guidelines**

#### **Cleanliness**

This device should be handled in a clean environment. The chip is resistant to solvents and may cleaned using approved industry standard practices.

## **Static Sensitivity**

Gallium Arsenide PIN diodes are ESD sensitive and can be damaged by static electricity. Proper ESD handling techniques should be used. These devices are rated Class 0, (0-199V) per HBM MIL-STD-883, method 3015.7 should be handled in a static-free environment.

## **General Handling**

The die has a polymer layer which provides scratch protection for the junction area and the anode air bridge. Die can be handled with plastic tweezers or picked and placed with a #27 tip vacuum pencil.

## Assembly Requirements using Electrically Conductive Silver Epoxy and Solder

The MA4GP907 is designed to be inserted onto hard or soft substrates with the junction/pad side down. It may be mounted onto a silk-screened circuit using electrically conductive silver epoxy, approximately 1-2 mils in thickness and cured at approximately 90°C to 150°C per manufacturer's schedule. For extended cure times, > 30 minutes, temperatures must be kept below 200°C.

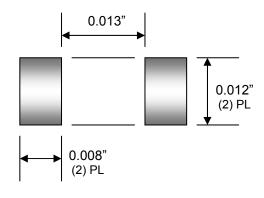
#### **Eutectic Die Attached**

Tin rich solders ( >30% Sn by weight ) are not recommended as they will scavenge gold from the contact pads exposing the tungsten metallization beneath and creating a poor solder connection. Indalloy or 80Au/20Sn type solders are acceptable. Maximum soldering temperature must be kept below 280°C for less than 10 seconds.

# Ordering Information

Part Number	Packaging
MA4GP907	Waffle Pack
MADP-000907-13050P	Pocket Tape

#### **Circuit Pad Layout**



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